

FLEXIBLE · DURABLE · CORROSION-FREE



Flexible nickel-clad microfilament stainless steel conductive braid material for ESD bond applications



ArmorLite is an innovative material ideally suited for ESD bonding as well as surge current grounding. The nickel-clad stainless steel microfilament material saves significant weight compared to standard QQ-B-575 copper material. A 100% ArmorLite bond strap, for example, is more than 70% lighter than a conventional plated copper solution of the same length.

Flexible, durable ArmorLite ESD bond straps are supplied in material blends optimized for the moderate current and resistance requirements of electrical potential bonding in aerospace applications. ArmorLite at 100% is the lightest weight of the four available blends. The 75/25 and 50/50 blends of ArmorLite and nickel copper improve current capacity for grounding applications at the cost of some additional weight. ArmorLite CF is a special construction of high-conductivity copper microfilaments with stainless steel cladding which offers optimal corrosion resistance, increased current capacity, and reduced resistance.

- Ultra-lightweight EMI/RFI braiding material for hightemperature applications -80°C to +260°C
- Microfilament stainless steel: 70% lighter than NiCu A-A-59569/QQB575
- Good electrical performance: shielding, conductivity, and grounding
- Commercial and military aerospace qualifications
- Superior flexibility and "windowing" resistance
- Strong: 70,000 psi (min.) tensile strength
- Outstanding lightning strike performance — ANSI/EIA-364-75-1997 Waveform 5B